

DATA ITEM DESCRIPTION

Title: MATERIAL IMPROVEMENT PROJECT (MIP) REPORT

Number: DI-MGMT-80258B

Approved Date: 20160608

AMSC Number: F9669

Limitation: N/A

DTIC Applicable: No

GIDEP Applicable: No

Preparing Activity: 11 (AFLCMC/EZSC)

Project Number: MGMT-2015-038

Applicable Forms: N/A

Use/Relationship: The Material Improvement Project Report is used by program management activities to resolve problem impeding deployment and efficient utilization of mission equipment. It also provides investigation results and problem analysis necessary for the correction of those deficiencies identified by the procuring activity.

- a. This Data Item Description (DID) contains the format, content, and intended use information for the data deliverable resulting from the work task described in the solicitation.
- b. This DID is applicable to all contracts to acquire MIP data resulting from government directed investigations.
- c. This DID interrelates with DI-PSSS-81535, *Deficiency Report (DR)*.
- d. This DID supersedes DI-MGMT-80258A.

(Copies of these documents are available online at <http://quicksearch.dla.mil>.)

Requirements:

1. Reference documents. The applicable issue of the documents cited herein, including their approval dates and dates of any applicable amendments, notices, and revisions, shall be as specified in the contract.
2. Format. The MIP Report shall be in the contractor's format.
3. Content. The MIP Report shall include the following:
 - a. MIP number
 - b. Service Report (SR) number
 - c. SR originator
 - d. Mission Design Series (MDS)/Nomenclature
 - e. Model, Equipment, Support Equipment, Trainer Designation
 - f. Part Number of deficient item
 - g. Serial Number (if applicable)
 - h. National Stock Number (NSN) of deficient item
 - i. Work Unit Code of deficient item
 - j. Problem description

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- k. Investigation results and problem analysis to include, as applicable:
 - (1) Visual inspection results
 - (2) Bench test results
 - (3) Source of failure (isolated to subassembly)
 - (4) Failure mode of the subassembly
- l. Conclusion. Analysis of events that led to the systems/equipment failure (i.e., manufacturing process/procedures, materials, test and inspection disciplines)
- m. Corrective action or recommended follow-on action shall include:
 - (1) Component Improvement Program tasks
 - (2) Engineering Change Proposal (ECP) number
 - (3) Class II change number
 - (4) Technical Order (TO) revision
- n. Exhibit disposition

End of DI-MGMT-80258B.